

L Number	Hits	Search Text	DB	Time stamp
1	64221	(ball bump bead) near20 spring	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 13:20
8	251445	test\$3 near20 (device IC circuit chip die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 13:22
15	1673	((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 14:41
22	1576	((((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @ad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:52
29	574	((((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @rlad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 14:43
36	1634	((((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @ad<20010821) (((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @rlad<20010821)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:51
43	577	((ball bump bead) near20 spring) and 439/\$.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:51
50	151	((ball bump bead) near20 spring) and 439/43-85.ccls.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:52
57	1576	((((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @ad<20010821) and @ad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:52
64	516	((((ball bump bead) near20 spring) and (test\$3 near20 (device IC circuit chip die))) and @ad<20010821) and @rlad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:53
71	50	((ball bump bead) near20 spring) and 439/43-85.ccls.) and @rlad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:53
78	139	((ball bump bead) near20 spring) and 439/43-85.ccls.) and @ad<20010821	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:53

85	146	((((ball bump bead) near20 spring) and 439/43-85.ccls.) and @rlad<20010821) (((ball bump bead) near20 spring) and 439/43-85.ccls.) and @ad<20010821)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/10 17:53
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